ABSTRACT

SEMICONDUCTOR DEVICE AND METHOD OF ITS MANUFACTURE

A method of manufacturing a semiconductor device comprises: a first step of interposing a thermosetting adhesive between a substrate 12 and a semiconductor chip 20 on which electrodes are formed; a second step of electrically connecting the interconnect pattern 10 and electrodes 22, and the anisotropic conductive material 16 is spreading out beyond the semiconductor chip 20 and is cured in the region of contact with the semiconductor chip 20; and a third step in which the region of the anisotropic conductive material 16 other than the region of contact with the semiconductor chip 20 is heated and the excess substrate is cut.

Fig 1.